

SMT power inductors

PID differential mode inductors

Series/Type: PID*-251M
Date: September 2022

Rated inductance 2 x 250 μ H
Construction

- Ferrite core
- Magnetically shielded
- Winding enamel copper wire
- Winding welded to terminals


Features

- Temperature range up to +150 °C
- High rated current
- Low DC resistance
- Functional isolation up to 500 V
- Suitable for lead-free reflow soldering as referenced in JEDEC J-STD 020E
- RoHS-compatible

Applications

- Industrial electronics
- Power over Data Line (PoDL) for 10BASE-T1L (IEEE 802.3 cg)
- Differential mode choke

Terminals

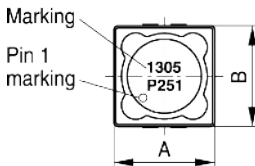
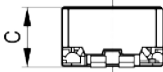
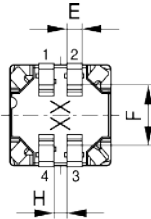
- Base material CuSn6P
- Lead-finish Sn (lead-free)
- Electro-plated

Marking

- Marking on component:
 PID75-251M and PID100-251M: Code letter "D", L value (in μ H), date of manufacture (YWWD), dot for Pin 1 identification
 PID120L-251M and PID120H-251M: Product series, code letter "D", L value (in μ H), date of manufacture (YWWD), two last digits of production order, dot for Pin 1 identification
 PID150H-251M: Code letter "D", L value (in μ H), date of manufacture (YWWD), dot for Pin 1 identification

Delivery mode and packing units

- Blister tape, wound on 330-mm \varnothing reel
 - 16-mm blister tape for PID75-251M
 - 24-mm blister tape for PID100-251M, PID120L-251M, PID120H-251M
 - 32-mm blister tape for PID150H-251M
- Packing unit:
 - 1000 pcs./reel for PID75-251M
 - 600 pcs./reel for PID100-251M
 - 350 pcs./reel for PID120L-251M
 - 250 pcs./reel for PID120H-251M
 - 175 pcs./reel for PID150H-251M

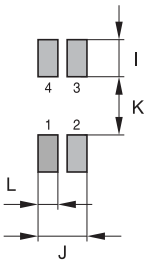
Dimensional drawing


IND1889-C-E

Ordering code	A	B	C
PID75-251M	7.5 max.	7.5 max.	4.8 max.
PID100-251M	10.4 max.	10.4 max.	6.3 max.
PID120L-251M	12.5 max.	12.5 max.	8.5 max.
PID120H-251M	12.5 max.	12.5 max.	10.5 max.
PID150H-251M	15.5 max.	15.5 max.	14.5 max.

Ordering code	E	F	H
PID75-251M	0.8 ±0.1	3.8 ±0.2	1 ±0.1
PID100-251M	1.5 ±0.2	6 ±0.2	1.3 ±0.2
PID120L-251M	1.75 ±0.2	7.2 ±0.2	1.5 ±0.2
PID120H-251M	1.75 ±0.2	7.2 ±0.2	1.5 ±0.2
PID150H-251M	2.0 ±0.2	8.0 ±0.2	1.8 ±0.2

Dimensions in mm

Layout recommendation


IND1890-D

Ordering code	I	J	K	L
PID75-251M	2.1	2.8	3.3	1.1
PID100-251M	2.4	4.5	5.7	1.7
PID120L-251M	3.1	5.8	6.8	2.3
PID120H-251M	3.1	5.8	6.8	2.3
PID150H-251M	4.15	6.6	7.4	2.55

Dimensions in mm

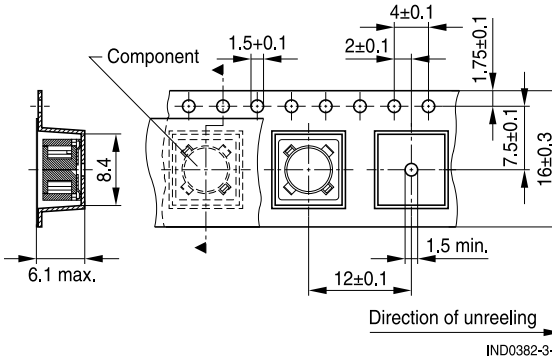
Circuit diagram


IND1998-D

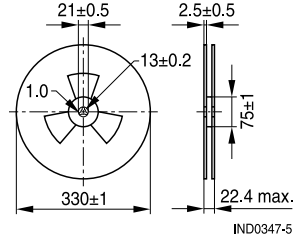
Taping and packing

PID75-251M

Blister tape

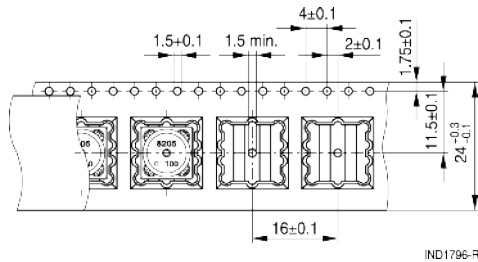


Reel

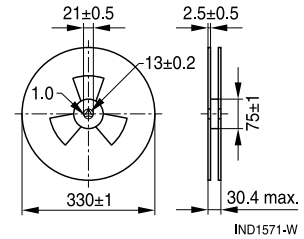


PID100-251M

Blister tape

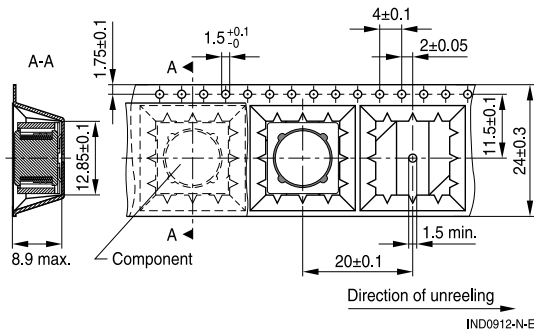


Reel

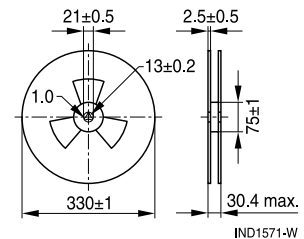


PID120L-251M

Blister tape

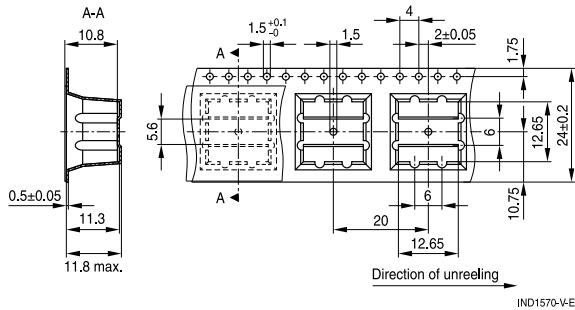


Reel



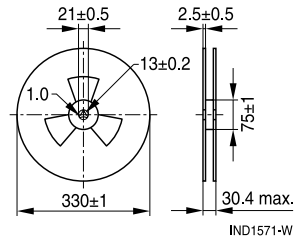
PID120H-251M

Blister tape



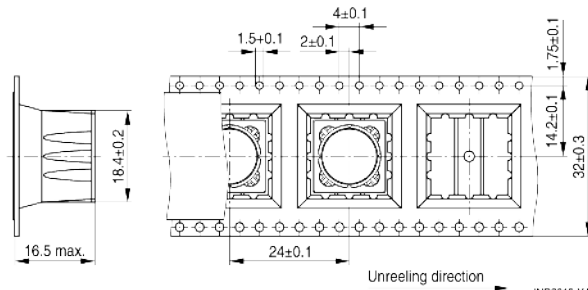
IND1570-VE

Reel



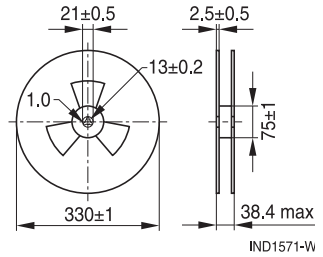
PID150H-251M

Blister tape



IND2019-YE

Reel



Technical data and measuring conditions

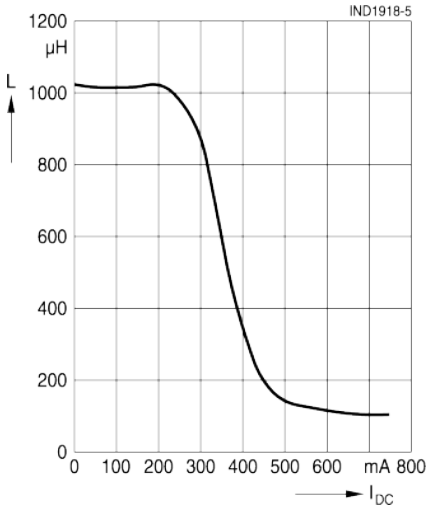
Rated inductance L_1, L_2	Measured with LCR meter Agilent 4284A (or equivalent) at frequency f_L , 0.1 V, 23 °C, 250 μ H per winding
Tolerance	$\pm 20\%$
Inductance L_{PoDL}	Typ. 1000 μ H, equivalent inductance when both windings are connected in series (measured in 1-4 with 2-3 shorted)
Operating temperature range	-40 °C to +150 °C (self-rise temperature included)
Rated current I_R	Max. typ. permissible DC with temperature increase of ≤ 40 K Method as per IEC62024-2, when both windings are connected in series (measured in 1-4 with 2-3 shorted)
Saturation current I_{Sat}	DC with inductance decrease $\Delta L/L_0$ of approx. 30%, when both windings are connected in series (measured in 1-4 with 2-3 shorted), typical values
DC resistance R_1, R_2 , (max.)	Measured at +23 °C, is specified per winding
Isolation (functional)	Tested with 500 V, 0.4 s by 100%; 3 s during qualification
Solderability (lead-free)	Dip and look method, Wetting of soldering area $\geq 95\%$ as referenced in EIA/IPC/JEDEC J-STD-002E
Resistance to soldering heat	as referenced in JEDEC J-STD-020E
Climatic category	40/150/56 (to IEC 60068-1)
Storage conditions	Mounted: -40 °C ... +150 °C Packaged: -25 °C ... +40 °C, $\leq 75\%$ RH
Weight	Approx. 0.9 g for PID75-251M Approx. 2.5 g for PID100-251M Approx. 4.2 g for PID120L-251M Approx. 5.0 g for PID120H-251M Approx. 10.5 g for PID150H-251M

Characteristics and ordering codes

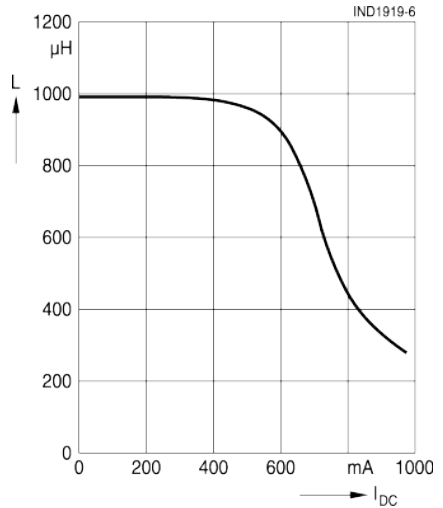
Size	IEEE 802.3 cg Power class	R _{DC,typ}	I _{Sat,typ}	I _{R,typ} (ambient temp.)	Internal code	Ordering code
mm		Ω	mA	mA		
7.5 x 7.5 x 4.8	10	2.25	360	270 (+25 °C) 250 (+85 °C) 240 (+105 °C)	B82472E6254M000	PID75-251M
10.4 x 10.4 x 6.3	11, 13	1.13	645	460 (+25 °C) 410 (+85 °C) 400 (+105 °C)	B82464E6254M000	PID100-251M
12.5 x 12.5 x 8.5	11, 13, 14	0.65	910	650 (+25 °C) 530 (+85 °C) 500 (+105 °C)	B82477E4254M000	PID120L-251M
12.5 x 12.5 x 10.5	13, 14	0.41	1160	820 (+25 °C) 675 (+85 °C) 635 (+105 °C)	B82477E6254M000	PID120H-251M
15.5 x 15.5 x 14.5	12, 14	0.27	1200	1200 (+25 °C) 1070 (+85 °C) 1040 (+105 °C)	B82480E8254M000	PID150H-251M

Inductance versus I_{DC} (typical values, series L)

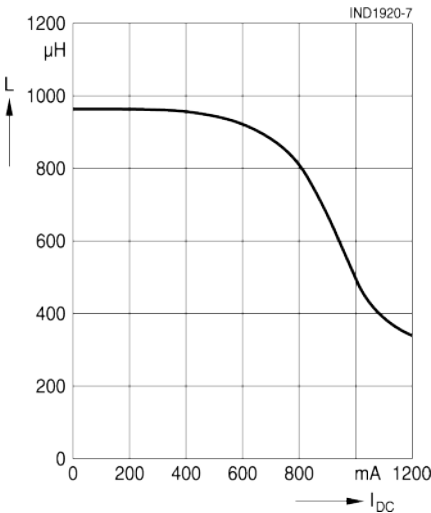
PID75-251M



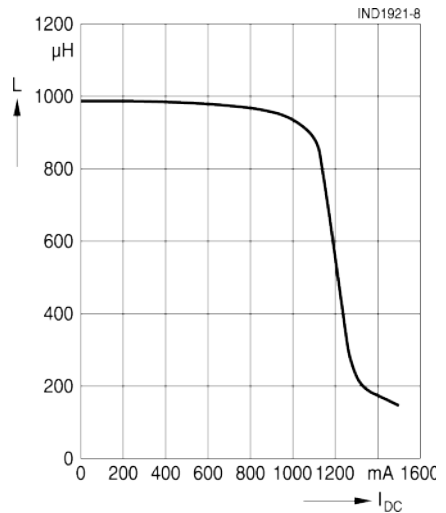
PID100-251M



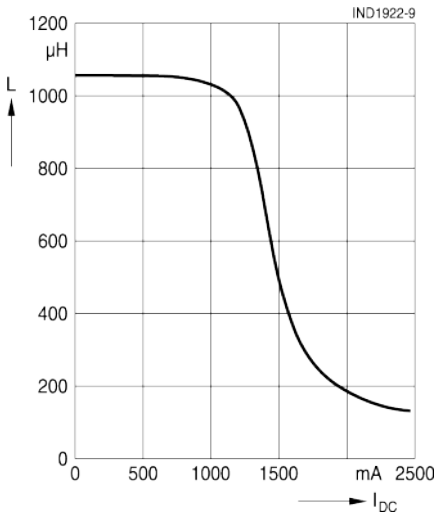
PID120L-251M



PID120H-251M



PID150H-251M



Cautions and warnings

- Please note the recommendations in our Inductors data book (latest edition) and in the data sheets.
 - Particular attention should be paid to the derating curves given there.
 - The soldering conditions should also be observed. Temperatures quoted in relation to wave soldering refer to the pin, not the housing.
- If the components are to be washed varnished it is necessary to check whether the washing varnish agent that is used has a negative effect on the wire insulation, any plastics that are used, or on glued joints. In particular, it is possible for washing varnish agent residues to have a negative effect in the long-term on wire insulation. Washing processes may damage the product due to the possible static or cyclic mechanical loads (e.g. ultrasonic cleaning). They may cause cracks to develop on the product and its parts, which might lead to reduced reliability or lifetime.
- The following points must be observed if the components are potted in customer applications:
 - Many potting materials shrink as they harden. They therefore exert a pressure on the plastic housing or core. This pressure can have a deleterious effect on electrical properties, and in extreme cases can damage the core or plastic housing mechanically.
 - It is necessary to check whether the potting material used attacks or destroys the wire, wire insulation, plastics or glue.
 - The effect of the potting material can change the high-frequency behaviour of the components.
 - Many coating materials have a negative effect (chemically and mechanically) on the winding wires, insulation materials and connecting points. Customers are always obligated to determine whether and to what extent their coating materials influence the component. Customers are responsible and bear all risk for the use of the coating material. TDK Electronics does not assume any liability for failures of our components that are caused by the coating material.
- Ceramics / ferrites are sensitive to direct impact. This can cause the core material to flake, or lead to breakage of the core.
- Even for customer-specific products, conclusive validation of the component in the circuit can only be carried out by the customer.
- Due to product design and applied manufacturing process, appearance, symmetry, and shape of not dimensioned details could vary within same lot, as well discoloration of housing is possible. TDK does not expect detrimental effects on product function or reliability. In case of conflicts, TDK reference standard shall prevail.

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2. We also point out that **in individual cases, a malfunction of electronic components or failure before the end of their usual service life cannot be completely ruled out in the current state of the art, even if they are operated as specified**. In customer applications requiring a very high level of operational safety and especially in customer applications in which the malfunction or failure of an electronic component could endanger human life or health (e.g. in accident prevention or life-saving systems), it must therefore be ensured by means of suitable design of the customer application or other action taken by the customer (e.g. installation of protective circuitry or redundancy) that no injury or damage is sustained by third parties in the event of malfunction or failure of an electronic component.
3. **The warnings, cautions and product-specific notes must be observed.**
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